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**INFORMATION DISCLOSURE
CITATION FORM FOR
PATENT APPLICATION
(FORM PTO-1449)
(Substitute)**

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Serial No.: 10/700,327

Applicant(s): Paul S. ANDRY et al.

Filing Date: 11/03/03

Group:

U.S. PATENTS

Initials	Patent Number	Issue Date	Name	Class	Sub-class	Filing date
/MW/	5,244,143	09/14/93	Ference et al.	X	X	
/MW/	5,775,569	07/07/98	Berger et al.			
/MW/	5,998,292	12/07/99	Black et al.			
/MW/	6,506,332	01/14/03	Pedigo			
/MW/	6,593,644	07/15/03	Chiu et al.			

FOREIGN PATENT DOCUMENTS

Initials	Document Number	Date	Country	Name	Translation? Yes/No/n/a

OTHER DOCUMENTS (Title, Author, Date, Pages, Etc., if known)

/MW/	"Filling the via hole of IC by VPES (Vacuum Printing Encapsulation Systems for stacked chip (3D Packaging), A. Okuno et al., 2002 Electronics Components and Technology Conference

Examiner's Signature: /Mary Wilczewski/

Date Considered: 07/07/2007

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